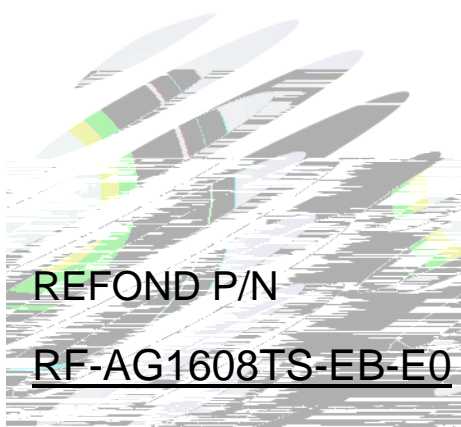
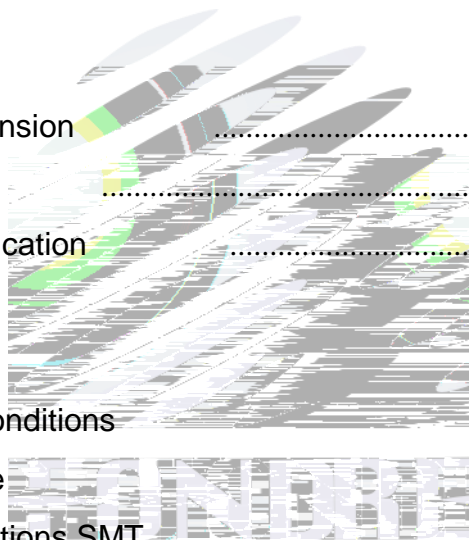


SPECIFICATION



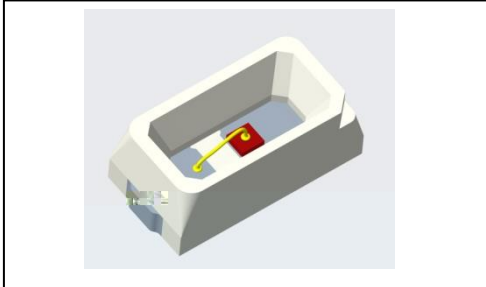
Contents

1. Description	
1.1 General Description	
1.2 Features	
1.3 Application	
1.4 Package Dimension	
1.5 Product Parameters	
1.6 Typical Optical Characteristics Curves	
2. Packaging	
2.1 Packaging Specification	
2.1.1 Carrier Tape Dimension	11
2.1.2 Reel Dimension	11
2.1.3 Label Form Specification	12
2.2 Moisture Resistant Packing	
2.3 Cardboard Box	
2.4 Reliability Test Items And Conditions	
2.5 Criteria For Judging Damage	
3. SMT Reflow Soldering Instructions SMT	
3.1 SMT Reflow Soldering Instructions SMT	
4. Handling Precautions	
4.1 Handling Precautions	



1. Description

1.1 General Description



The Colour LED which was fabricated using a amber chip Package Dimension :
1.6mmX0.8mmX0.55mm.

LED

1.6mmX0.8mmX0.55mm

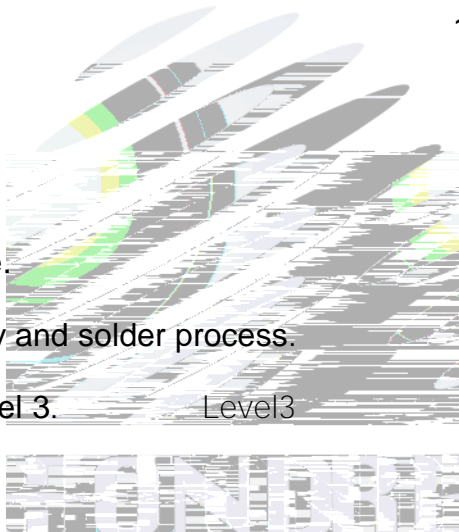
1.2 Features

Extremely wide viewing angle.

Suitable for all SMT assembly and solder process.

Moisture sensitivity level: Level 3.

RoHS compliant. RoHS



SMT

Level3

1.3 Application

Optical indicator.

Switch and symbol, display.

General use.

1.4 Package Dimension

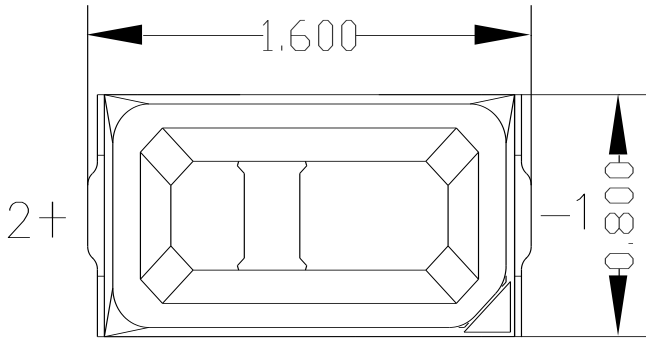


Fig.1-1 Top view

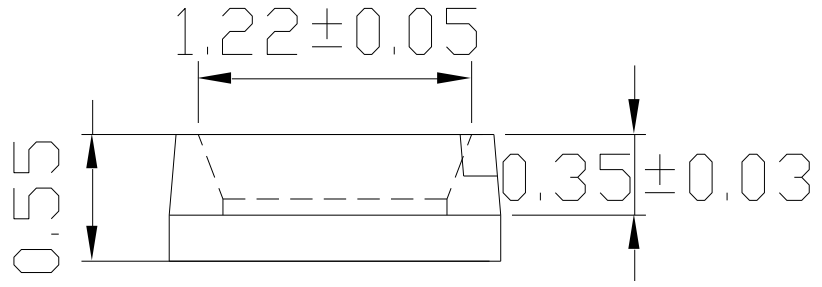


Fig.1-2 Side view

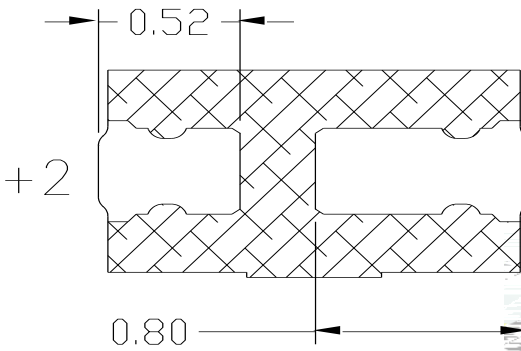


Fig.1-3 Bottom view

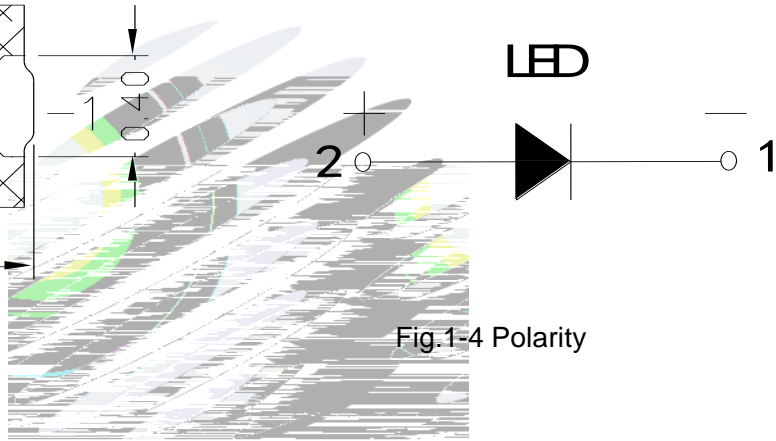


Fig.1-4 Polarity

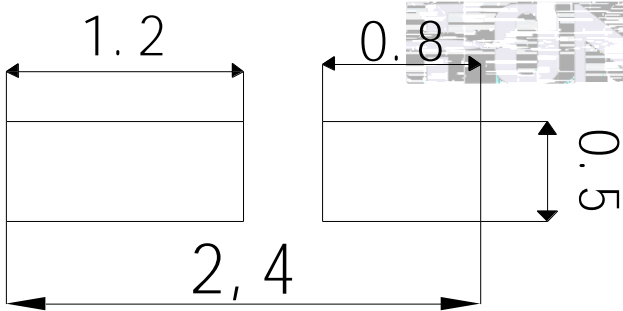


Fig.1-5 Soldering patterns

Notes

1. All dimensions units are millimeters.

All dimensions tolerances are 0.2mm unless otherwise noted.

±0.2

1.5 Product Parameters

Table 1-1 Electrical / Optical Characteristics at Ts=25°C

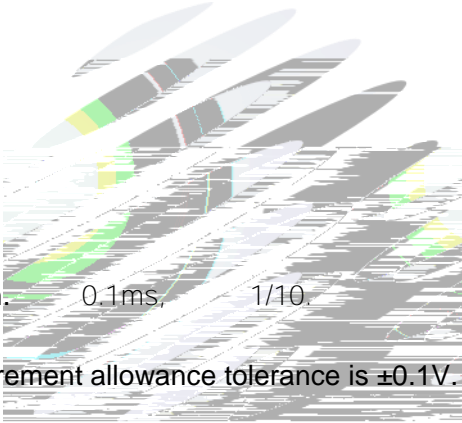
Item	Test Condition	Symbol	Value			Unit	
			Min. ()	Typ.	Max.		
Spectral Half Bandwidth	$I_F=20\text{mA}$		--	15	--	nm	
Forward Voltage	$I_F=20\text{mA}$	V_F	A1	1.6	--	1.7	V
			A2	1.7	--	1.8	V
			B1	1.8	--	1.9	V
			B2	1.9	--	2.0	V
			C1	2.0	--	2.1	V
			C2	2.1	--	2.2	V
			D1	2.2	--	2.3	V
			D2	2.3	--	2.4	V
Dominant Wavelength	$I_F=20\text{mA}$	λ_D				nm	
						nm	
Luminous Intensity	$I_F=20\text{mA}$	I_v	G00	100	--	150	mcd
			H00	150	--	230	mcd
			I00	230	--	350	mcd
			J00	350	--	530	mcd
			K00	530	--	800	mcd
Viewing Angle	$I_F=20\text{mA}$		--	120	--	deg	
Reverse Current	$V_R=5\text{V}$	I_R	--	--	10	A	
Thermal Resistance.	$I_F=20\text{mA}$	R_{THJ-S}	--	--	450	/W	

Notes : $V_R=5\text{V}$ For test conditions. $V_R=5\text{V}$

Table 1-2 Absolute Maximum Ratings at Ts=25°C

Parameter	Symbol	Rating	Units
Power Dissipation			

Notes

- 1/10 Duty cycle, 0.1ms pulse width.  0.1ms, 1/10.
2. The above forward voltage measurement allowance tolerance is $\pm 0.1V$. $\pm 0.1V$.
3. The above dominant wavelength measurement allowance tolerance is $\pm 2nm$. $\pm 2nm$.
4. The above luminous intensity measurement allowance tolerance $\pm 10\%$. $\pm 10\%$.
5. Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product.
6. All measurements were made under the standardized environment of Refond.
7. When the LEDs are in operation the maximum current should be decided after measuring the package temperature, junction temperature should not exceed the maximum rate. LED

1.6 Typical Optical Characteristics Curves

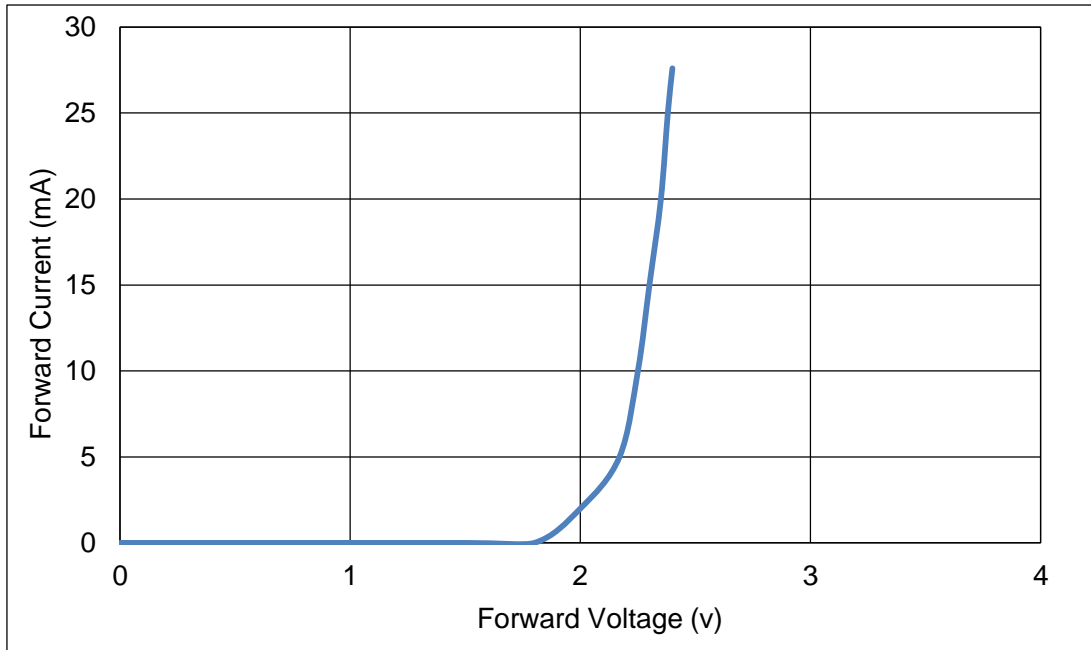


Fig 1-6 Forward Voltage Vs Forward Current

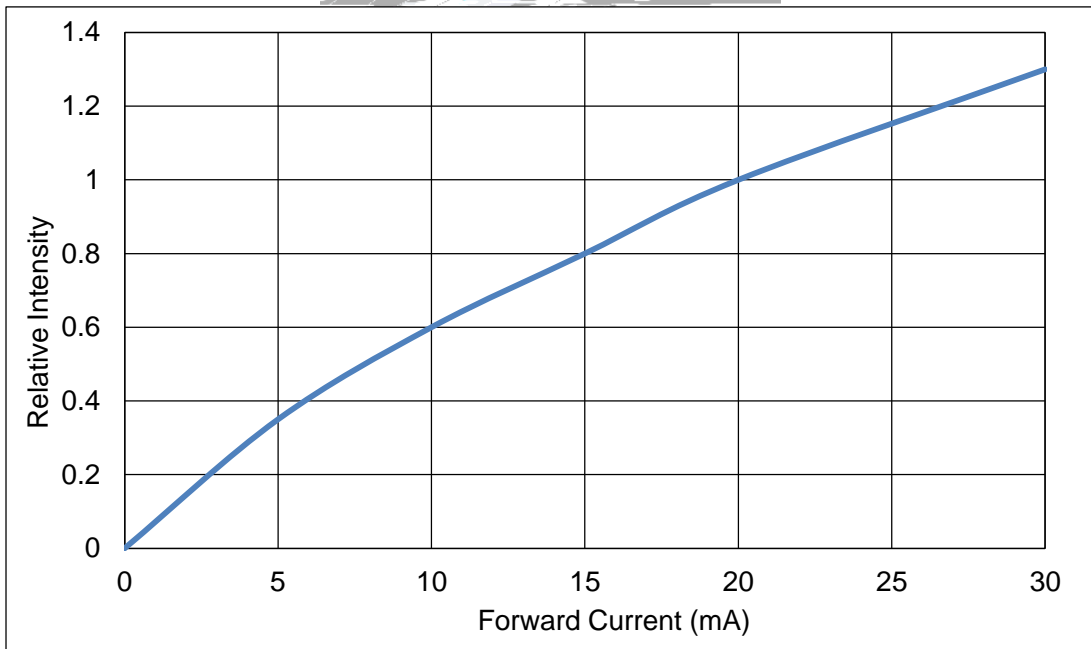
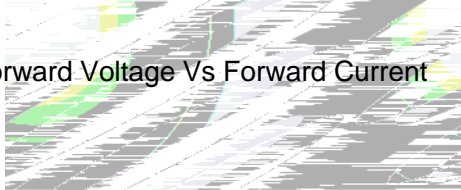


Fig 1-7 Forward Current Vs Relative Intensity

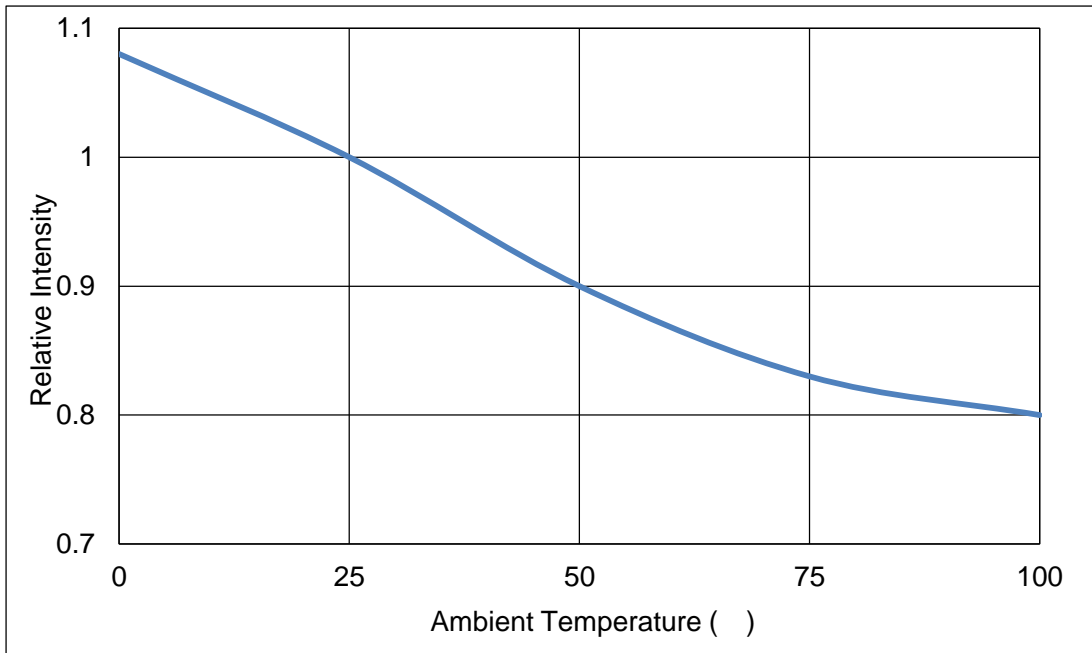


Fig 1-8 Pin Temperature Vs Relative Intensity

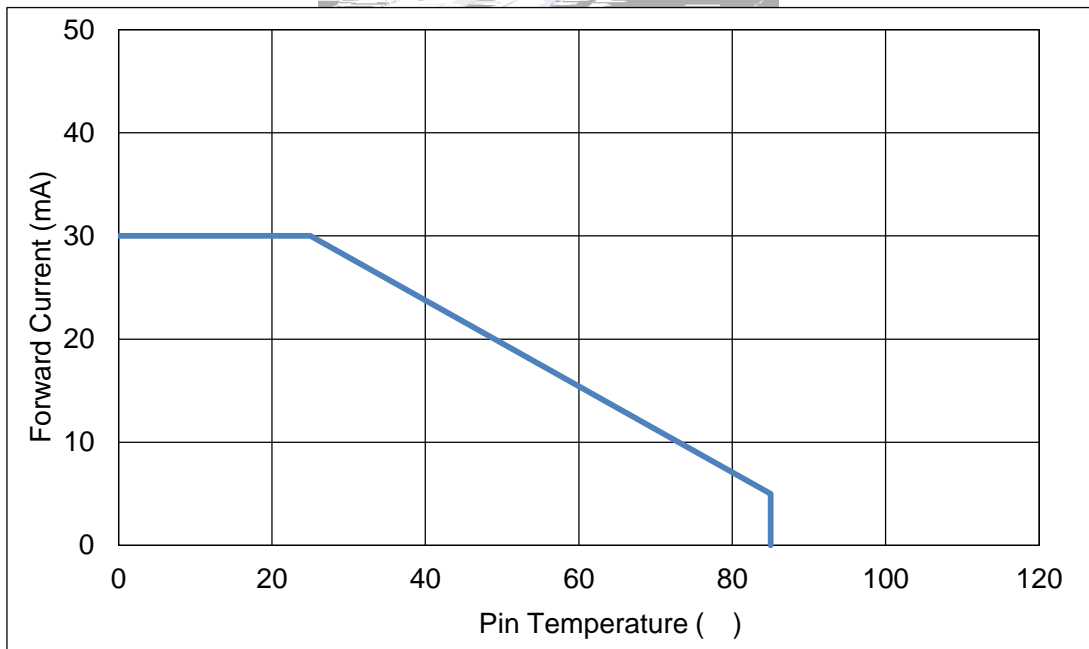
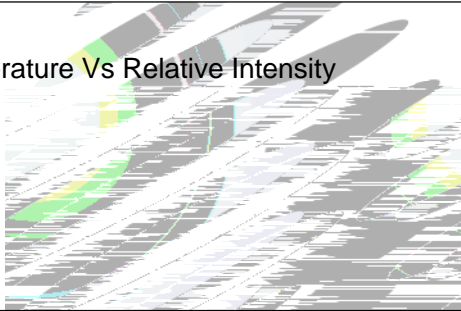
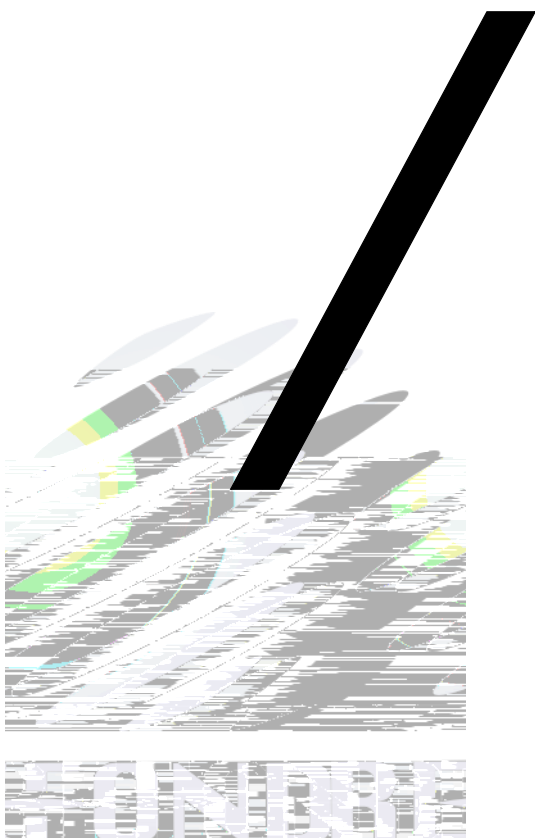


Fig 1-9 Pin Temperature Vs Forward Current



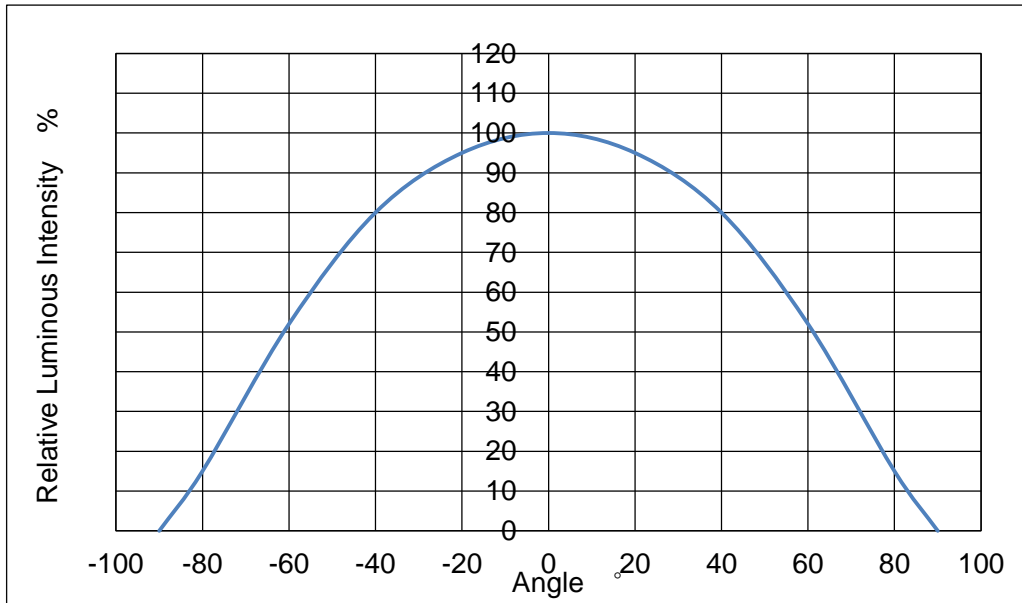
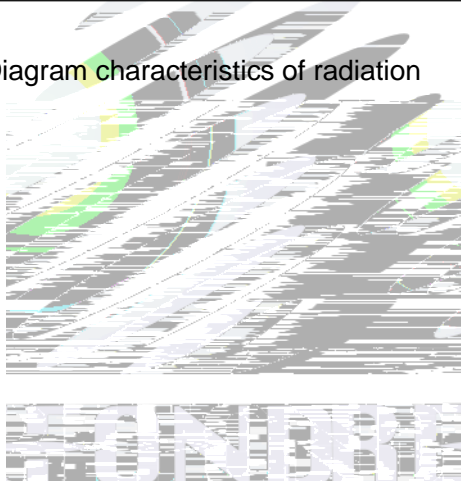


Fig 1-12 Diagram characteristics of radiation



2. Packaging

2.1 Packaging Specification

Package:4000pcs/reel.

4000pcs

2.1.1 Carrier Tape Dimension

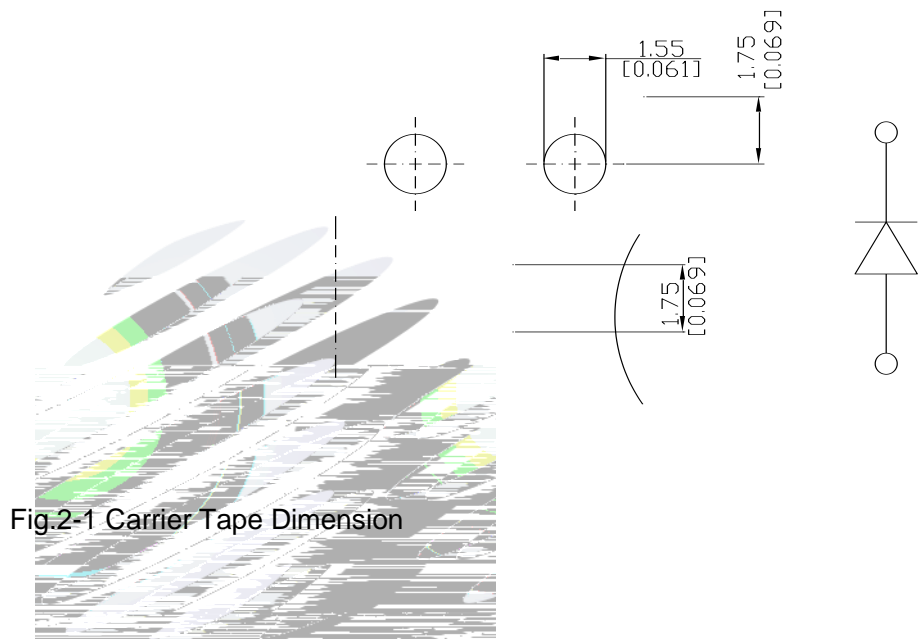


Fig.2-1 Carrier Tape Dimension

2.1.2 Reel Dimension

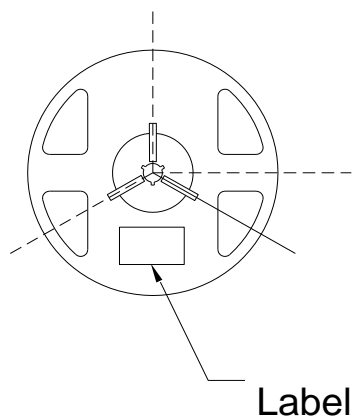


Fig.2-2 Reel Dimension

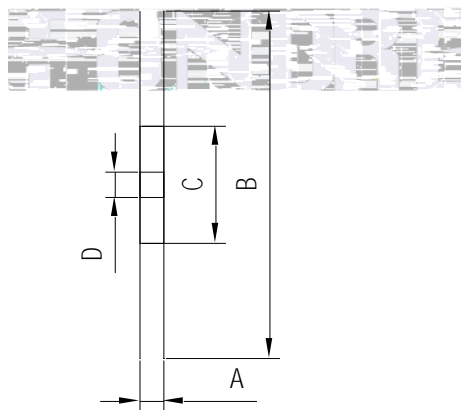


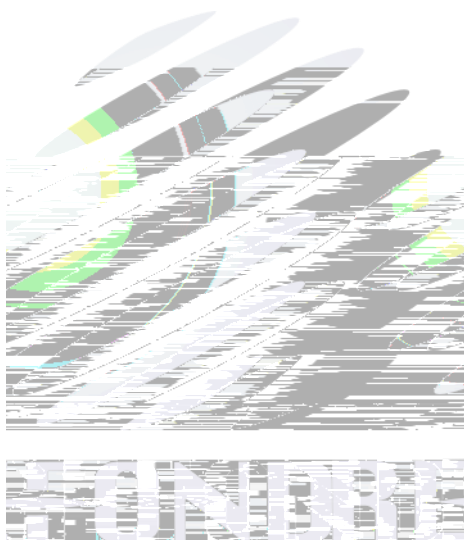
Table 2-1 Dimension

A	8.0±0.1mm
B	178±1mm
C	60±1mm
D	13.0±0.5mm

Notes

The tolerances unless mentioned ±0.1mm. Unit : mm

±0.1



2.3 Cardboard Box

Fig.2-5 Cardboard Box

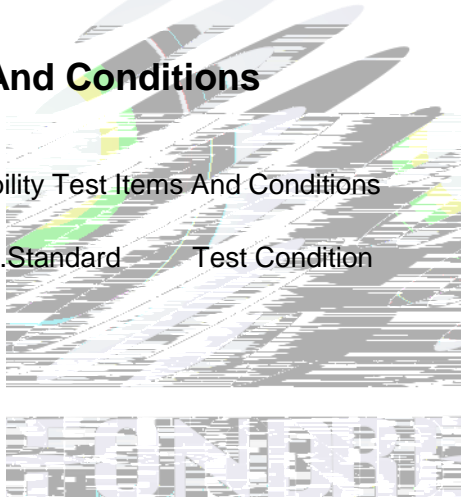
2.4 Reliability Test Items And Conditions

Table 2-3 Reliability Test Items And Conditions

Test Items

Ref.Standard

Test Condition



2.5 Criteria For Judging Damage

Table 2-4 Criteria For Judging Damage

Test Items	Symbol	Test Condition	Criteria For Judgement	
			Min.	Max.
Forward Voltage	V_F	$I_F=20mA$	-	U.S.L*)x1.1
Reverse Current	I_R	$V_R= 5V$	-	U.S.L*)x2.0
Luminous Flux		$I_F=20mA$	L.S.L*)x0.7	-

Notes

1.U.S.L: Upper standard level

L.S.L: Lower standard level

2.The above reliability tests is based on the verification of a single/strip LED of Refond's existing experimental platform,the reliability experiment was taken under good heat dissipation conditions. When customers applies the LED to the series and parallel circuit,should take consideration of all the factors such as the current, voltage distribution, heat dissipation and others.

/ LED

LED

3.The technical information shown in the data sheets is limited to the typical characteristics and circuit examples of the referenced products. It does not constitute the warranting of industrial property nor the granting of any license.

3. SMT Reflow Soldering Instructions SMT

3.1 SMT Reflow Soldering Instructions SMT

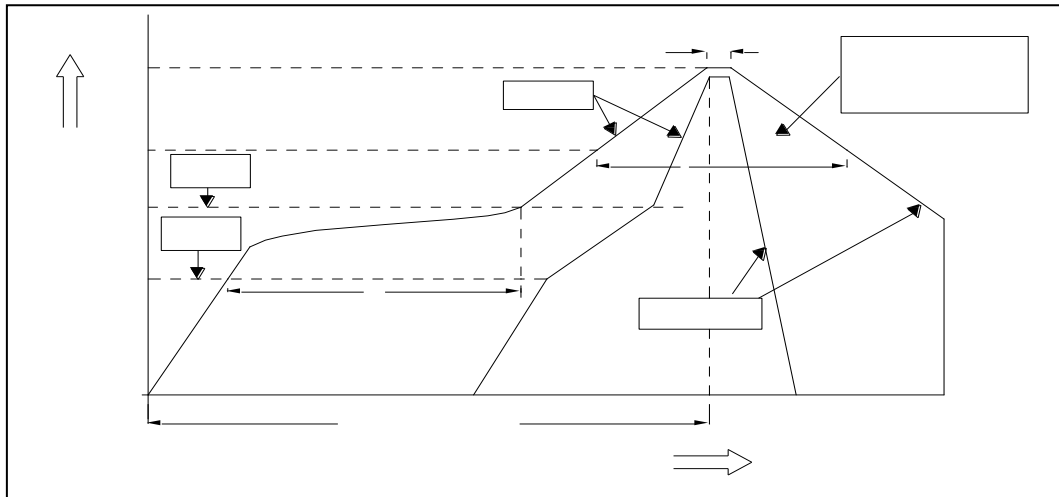


Fig.3-1 SMT Reflow Soldering Instructions SMT

Table 3-1 Parameter

Average temperature rise speed	T_{sm}	T_p	3 °C/	Max 3 °C/ s
Preheating: minimum temperature	(T_{smin})		150 °C	
Preheating: Max temperature	(T_{smx})		200 °C	
Preheating: Time	T_{smin}	T_{smx}	60 - 120	60s-120s
Time limited to maintain high temperature: the temperature			(T_L) 217 °C	
Time limited to maintain high temperature: The Time			(t_l) 60 - 150 60s-150s	
Peak /Classification of temperature:	/		(T_p) 260 °C	
Time limit classification of peak temperature time			t_p 10 Max 10s	
Hold time within 5 °C with the actual peak temperature (TP)			(T_p) 30 Max 30s	
5 °C				
Cooling speed			6 °C/ Max 6 °C/ s	
Needed time from 25 °C to T_p	25 °C		8 Max 8 minutes	

Notes

(1)Reflow soldering should not be done more than twice. If more than 24 hours between the two solderings , LED will be damaged. 24 LED

(2)When soldering , do not put stress on the LEDs during heating.

3.1.1 Soldering Iron

(1) When do soldering by hand, keep the temperature of iron below less 300°C less than 3 seconds. 300 3

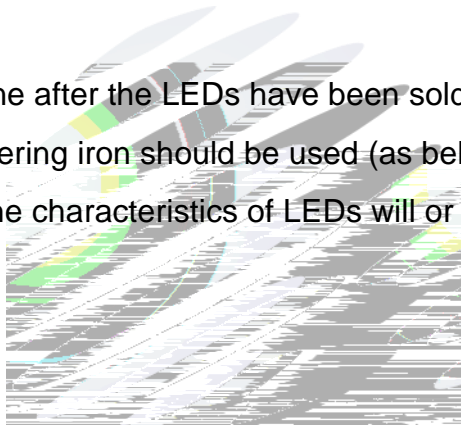
(2) Soldering by hand should be done only one time.

3.1.2 Repairing

Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable,a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or not be damaged by repairing.

LED

LED



3.1.3 Cautions

(1) Components should not be mounted on-warped (non coplanar) portion of PCB. After soldering, do not warp the circuit board.LED PCB

(2) Do not apply mechanical force or excess vibration during the cooling process to normal temperature after soldering. Do not rapidly cool device after soldering.

4. Handling Precautions

4.1 Handling Precautions

(1) LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating usage material. This is provided for informational purposes only and is not a warranty or endorsement. LED 100PPM.

(2) In order to prevent external material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than 900PPM, the single content of Chlorine element is required to be less than 900PPM, the total content of Bromine element and Chlorine element in the external materials of the application products is required to be less than 1500PPM. This is provided for informational purposes only and is not a warranty or endorsement.



(3) VOCs (Volatile organic compounds) emitted from materials used in the construction of fixtures can penetrate silicone encapsulants of LEDs and discolor when exposed to heat and photonic energy. The result can be a significant loss of light output from the fixture. Knowledge of the properties of the materials selected to be used in the construction of fixtures can help prevent these issues. Refond advises against the use of any chemicals or materials that have been found or are suspected to have an adverse effect on device performance or reliability. To verify compatibility, Refond recommends that all chemicals and materials be tested in the specific application and environment for which they are intended to be used. Attaching LEDs, do not use adhesives that outgas organic vapor. LED

LED

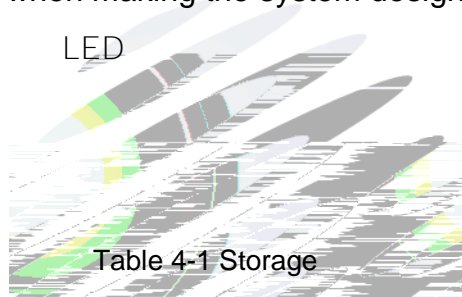
LED

LED

(4) In designing a circuit, the current through each LED can not exceed the absolute maximum rating specified for each LED. In the meanwhile, resistors for protection should be applied, otherwise slight voltage shift will cause big current change, burn out may happen. The driving circuit must be designed to allow forward voltage only when it is ON or OFF. If the reverse voltage is applied to LED, migration can be generated resulting in LED damage. LED

LED

(5) Thermal Design is paramount importance because heat generation may result in the Characteristics decline, such as brightness decreased, Color change and so on. Please consider the heat generation of the LEDs when making the system design. LED



(6) Storage

Conditions		Temperature	Humidity	Time
Storage	Before Opening Aluminum Bag	30	75%	Within 1 Year From Date
	After Opening Aluminum Bag	30	60%	168hours 168
Baking		60±5	-	24hours 24

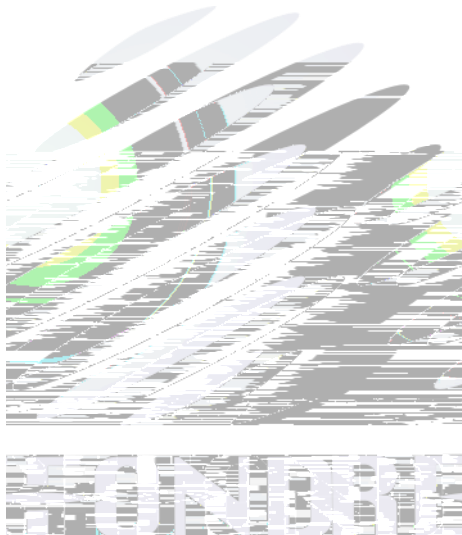
(7) If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time , baking treatment should be performed after unpacking and based on the following condition (60±5) °C for above 24 hours.

60±5

24

(8) Similar to most Solid state devices; LEDs are sensitive to Electro-Static Discharge (ESD) and Electrical Over Stress (EOS). LED

(9) Other points for attention, please refer to our relevant information.



Version History/

Date	Revisor	Version	Verifier	Remarks
2019.09.17		E0		



Declare

This specification is written both in English and in Chinese and the latter is formal.